

General Description

The PAE0704EU is designed with latest Punch-Through process TVS technology to protect voltage sensitive components from ESD. Excellent clamping capability, low leakage, and fast response time provide best in class protection on designs that are exposed to ESD. Because of its small size, it is suited for use in cellular phones, MP3 players, digital cameras and many other portable applications where board space comes at a premium. Also because of its low capacitance, it is suited for use in high frequency designs such as USB 2.0 high speed, USB 3.0 super speed, VGA, DVI, HDMI, eSATA and other high speed line applications.

It has been specifically designed to protect sensitive components which are connected to data and transmission lines from overvoltage caused by ESD(electrostatic discharge), and EFT (electrical fast transients).

Feature

- Peak Power Dissipation 60 W (8 x 20 us Waveform)
- Stand-off Voltage: 7.0 V
- Low capacitance (<0.4pF) for high-speed interfaces
- No insertion loss to 20.0GHz
- Replacement for MLV (0402)
- Protects I/O Port
- Low Clamping Voltage
- Low Leakage
- Low Capacitance
- Meets MSL 1 Requirements
- ROHS compliant
- Solid-state Punch-Through TVS Process technology

Application

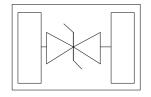
- High Speed Line: USB1.0/2.0/3.0/3.1, VGA, DVI, SDI,
- High Definition Multi-Media Interface (HDMI1.3/1.4/2.0/2.1)
- Serial and Parallel Ports
- Notebooks, Desktops, Servers
- Projection TV
- Cellular handsets and accessories
- Portable instrumentation
- Peripherals

Protection solution to meet

- IEC61000-4-2 (ESD): ±20kV (air), ±20kV (contact)
- IEC61000-4-5 (Lightning) 3A (8/20μs)

DFN-1006







Maximum Ratings (TA=25°C Unless otherwise specified)

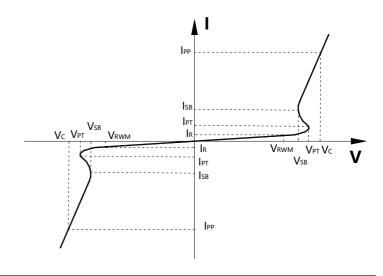
Parameter	Symbol	Value	Unit
Peak Pulse Power (tp=8/20μs waveform)	PPP	60	Watts
Peak Pulse Current (tp=8/20μs waveform)	I_{PP}	3	A
Lead Soldering Temperature	TL	260 (10 sec.)	$^{\circ}$
Operating Temperature Range	Tı	- 55 ∼ 150	${\mathbb C}$
Storage Temperature Range	Tstg	- 55 ∼ 150	${\mathbb C}$
Lead Solder Temperature – Maximum (10 Second Duration)	$T_{\rm L}$	260	$^{\circ}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

> Electrical Characteristics (TA=25°C Unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
V_{RWM}	Reverse Working Voltage	Pin1 to Pin2;Pin2 to Pin1			7	V
V D 1 70	Dynah Through Voltage	IT = 1 mA		8.5		V
V PT	V _{PT} Punch-Through Voltage	Pin1 to Pin2;Pin2 to Pin1		8.3		
т	Davianca I calcada Cumant	$V_{RWM} = 7V$		0.1	0.1).1 μΑ
1 _R	I _R Reverse Leakage Current	Pin1 to Pin2;Pin2 to Pin1			0.1	
		$I_{PP} = 1A$, $tp = 8/20 \mu s$		11.5	13	V
37	Clausius Valtasa	Pin1 to Pin2;Pin2 to Pin1			15	v
$V_{\rm C}$	V _C Clamping Voltage	$I_{PP} = 3A$, $tp = 8/20 \mu s$		17	20	V
		Pin1 to Pin2;Pin2 to Pin1				
C _J Junction Capacitan	C. Investiga Constitution	$V_R = 0V, f = 1MHz$		0.26	0.4	"E
	Junction Capacitance	Pin1 to Pin2;Pin2 to Pin1		0.20	0.4	pF

Symbol	Parameter
Vrwm	Working Peak Reverse Voltage
V _{PT}	Punch-Through Voltage@ IPT
VsB	Snap-Back Voltage@ I _{SB}
$V_{\rm C}$	Clamping Voltage @ IPP
I_T	Test Current
Irm	Leakage current at VRWM
Ірр	Peak pulse current
Co	Off-state Capacitance
C _J	Junction Capacitance

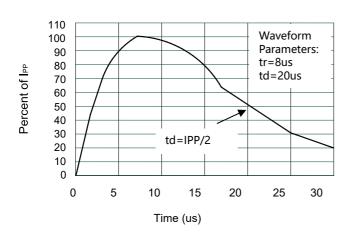


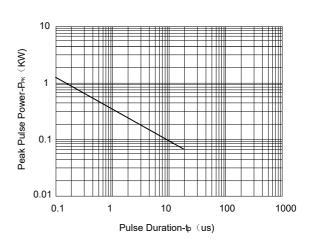
^{*}Other voltages may be available upon request.

^{1.} Non-repetitive current pulse, per Figure 1.



Typical Characteristics

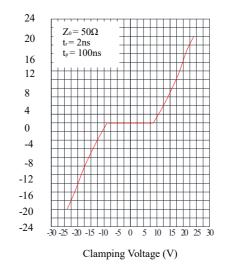




Pulse Waveform

110 100 % of Rated Power or Ipp 90 80 70 60 50 40 30 20 10 0 25 125 50 75 100 150 Ambient Temperature-T A (°C)

Non-Repetitive Peak Pulse Power vs. Pulse Time



Power Derating Curve

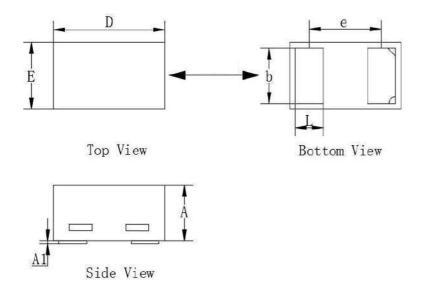
TLP Measurement

TLP Current (A)



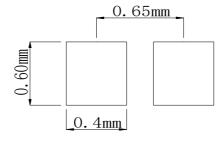
> Package Information (DFN1006)

Case Material: Molded Plastic. UL Flammability



DIM	Millimeters		
	Min	Max	
A	0.37	0.55	
A 1	0.00	0.05	
D	0.95	1.05	
E	0.48	0.65	
b	0.35	0.55	
e	0.65TYP		
L	0.15	0.35	

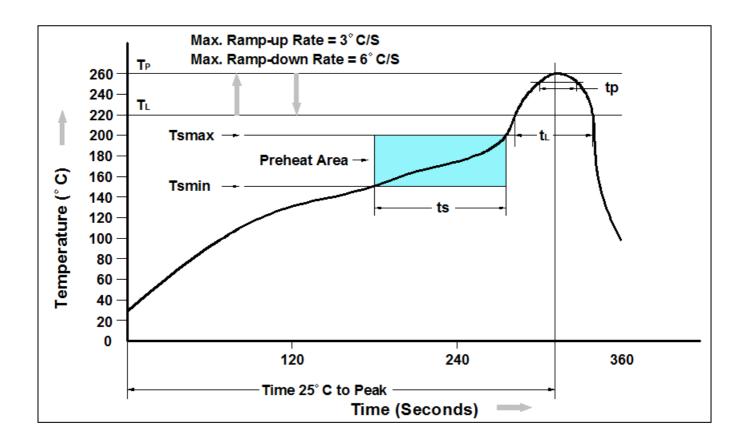
Recommended Pad outline



Ordering Information

Part Number	Description	Quantity
PAE0704EU	DFN1006 Reel	10000 pcs

> Recommand IR Reflow Soldering Thermal Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Average Ramp-up Rate (tLto tP)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds
Peak Temperature	260°C +0°C / -5°C
Time (tP) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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